



Mitsubishi Electric US, Inc. to exhibit at APEC 2018 in San Antonio, TX

CYPRESS, California – February 28th, 2018 – [Mitsubishi Electric US, Inc.](#), [Semiconductor and Device](#) Division will exhibit for the first time at Applied Power Electronics Conference ([APEC](#)) in San Antonio, March 5-7, 2018. The Semiconductor and Device Group will display its full lineup of power semiconductor products (formerly the Mitsubishi Products and Accessories Division of Powerex, Inc.) in booth #919.

The full lineup of products on display includes: the revolutionary new 7th Generation IGBTs, G1 Series IPMs, Version 6 DIIPMs (Dual Inline Package Intelligent Power Module), SLIMDIPs (Slim Dual Inline Package), DIIPM+, J1-Series Automotive modules, X-Series High Voltage IGBTs (Insulated Gate Bipolar Transistor), and SiC (Silicon Carbide) solutions.

In addition, two papers will be presented by the MEUS Application Engineering Team:

Dual High Voltage IGBT Modules with Metal Casting Direct Bonding (MCB) Baseplate
Presented by Junya Sakai, Eric Motto, and Mike Rogers
Wednesday, March 7, 2018, 16:35-17:00, Room 213

Exhibitor Seminar: Latest Power Semiconductor Packaging and Chip Technology
Presented by Eric Motto
Wednesday, March 7, 2018, 12:00-12:30p, Room 217D

About Mitsubishi Electric US Semiconductor & Device Division

Mitsubishi Electric US, Inc.'s Semiconductor & Device Division (SDD) offers a broad portfolio of semiconductor and electronic devices that provide: advanced information processing and telecommunications, highly efficient power production from both traditional and renewable energy sources, smart grids that distribute power more effectively, hybrid and electric vehicles that change the way that we commute, efficient industrial and automation applications that lower equipment costs while improving reliability and ground breaking efficiency gains in home appliances that reduce our cost of living and reduce the harmful impact on our environment.

The division offers next-generation optical devices that support today's rapidly evolving optical telecommunications networks. They include high-frequency gallium nitride, gallium arsenide and silicon RF devices used in a variety of applications from two-way radios to telecommunications satellites. The division also provides leading-edge color TFT-LCD modules designed for high reliability and superior visibility. Mitsubishi Electric's power modules implement technology that is at the forefront semiconductor industry. The latest innovations use extremely efficient Si and SiC chip technology as well as revolutionary packaging techniques to provide extremely efficient and reliable solutions for a more affluent, comfortable, efficient, and environmentally friendly society. Mitsubishi Electric's TFT-LCD modules deliver exceptional performance and excellent color quality in a broad range of indoor and outdoor operating environments. They can be used in such industrial applications as factory automation, agriculture, construction, marine, and aviation. Most recently, the division added contact image sensors for machine vision applications to its product line. Additional information is available at <http://us.mitsubishielectric.com/semiconductors/en/>. Mitsubishi Electric US group companies have roughly 31 locations throughout North America with approximately 4,000 employees.

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